

PTC

Material Data Sheet

Product Class	Sensors SMD B593xxA*; B594xxA* (lead-free ceramic) 14.10.2019						
Date							
IMDS ID if available							
Version	5.07		1				
Product Part (IMDS: semi component)	Material Class (IMDS: Material)	Material (Classification) VDA 231	Substance	TMPS**) [wt%]	CAS if applicable	typical mass of material [wt-%]	Traces see 1)
Active Part	Ceramic	3B	Ba-titanates Sr-titanates Ca-titanates others*)	79 10 10 1	12047-27-7 12060-59-2 12049-50-2	79.62	
Termination	Composite	4D	Ag Epoxy	85 15	7440-22-4 25036-25-3	9.3	
	Heavy Metal	1C14	Ni	100	7440-02-0	5.58	
	Heavy Metal Composite	1C8 4D	Sn Ag Glass frit (lead-boro-silicate)	93 7	7440-31-5 7440-22-4	4.5 0.93	
	Heavy Metal	1C2	Cr	100	7440-47-3	0.07	
	<u> </u>	ı	l	<u> </u>	Sum of total	100	1
						B59407A115*, B59421A075*, B59421A085*, B59421A095*, B59421A105*, B59421A115*, B59421A125*, B59451A115*	
Not part of a Product (Class						
Contact	Ronner Christoph Important remarks:						
Division	PPD Q QM 1) The declaration limit is 0.1% as defined by IEC 62474 (IEC PAS 61906). Traces						
Address	8530 Deutschlandsberg, AUSTRIA product parts, substances etc. that are below a percentage of 0.1 % by weight regulated.						weight, if not otherwise
Tel: mailto: 443 3462 800 2139 functional.ppd-eqpm.db@tdk-electronics.tdk.com *) others: .(not declarable or prohibited substances acc. GADSL) **) typical mass percentage of substance **) typical mass percentage of substance **) typical ma							herein are based on our or binding product RONICS AG AND ITS ON OR WARRANTY, ITHE STATEMENTS TO ANY
			tible means that products are com	patible with the requirer			of Directive 2011/65/EU
·			nnex III: (☑ valid ☐ not valid)			•	
□ no exemptions; □ Exemption 6 (a): Le □ Exemption 6 (b): Ce □ Exemption 7 (c)-I: Le □ Exemption 7 (c)-II: Le □ Exemption 7 (c)-II: Le	ead as an alloying element in ad as an alloying element in opper alloy containing up to ead in high melting temperat ectrical and electronic comp and in dielectric ceramic in ce and in dielectric ceramic in ce	n steel for machining purpose n aluminium containing up to 4 % lead by weight; ure type solder (i.e. lead-bas onents containing lead in a c apacitors for a rated voltage apacitors for a rated voltage	es and in galvanized steel containing up 0,4 % lead by weight; ed alloys containing 85 % by weight or plass or ceramic other than dielectric cer of 125 V AC or 250 V DC or higher; of less than 125 V AC or 250 V DC;	to 0,35 % lead by weight; more lead); amic in capacitors, e.g. pie		lass or ceramic matrix compo	bund;
	ead in solders to complete a above		between semiconductor die and carrier v	vitnin integrated circuit Flip	Chip packages;		